

# **PRODUCT SPECIFICATION**

# 16X1 CHARACTERS LCD MODULE MODEL: C1601C7SGW6B-B0 Ver:1.3

- < <>> Preliminary Specification
- < <> Finally Specification

R'S APPROVAL
DATE:

APPROVED	PM	PD	PREPARED
BY	REVIEWED	REVIEWED	BY
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# **Revision Status**

Version	Revise Date	Page	Content	Modified By
Ver 1.0	2014-07-25		First Issued	
Ver 1.1	2014-08-19	21	Add Packing Instruction	
Ver 1.2	2014-11-24		Modify the PCB, Improve the BackLight	
Ver 1.3	2014-12-09		Modify the PCB, Improve the BackLight, Change the LCD;	

	Issued Date:2014-12-09 Doc. No.:
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## 1. Features

The features of LCD are showed as follows

: STN/ Blue/ Transmissive/ Negative \* Display mode

: 6 O'clock

- \* Controller IC : SPLC780D1-001(English-Japanese)
- \* Display format : 16X1 Characters
- \* Interface Input Data : 4 bit or 8 bit MPU
- \* Driving Method : 1/16Duty, 1/5Bias
- \* Viewing Direction
- : 1 LED/Side White
- \* Backlight
- \*Sample NO. : C1601C7SGW6B-B0\_02/20141206

# 2. MECHANICAL SPECIFICATIONS

ltem	Specification	Unit
Module Size	122(W) x 44(H) x 13.0 (D)	mm
Viewing Area	99(W) x 13(H)	mm
Activity Display Area	94.84(W) x 9.66(H)	mm
Character Font	5x8 Dots	-
Character Size	4.84(W)x8.06(H)	mm
Character Pitch	6(W)x8.56(H)	mm
Dot Size	0.92(W)x1.1(H)	mm

# **3. ELECTRICAL SPECIFICATIONS**

### 3-1 ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C)

Item	Symbol	Min	Max	Unit
Supply Voltage For Logic	Vdd	-0.3	+7.0	V
Supply Voltage For LCD Drive	V <sub>LCD</sub>	Vdd-10.0	Vdd+0.3	V
Input Voltage	Vin	-0.3	Vdd+0.3	V
Operating Temp.	Тор	-20	+70	°C
Storage Temp.	Tst	-30	+80	°C

\*. NOTE: The response time will be extremely slow when the operating temperature is around  $-10^{\circ}$ C, and the back ground will become darker at high temperature operating.

#### **3-2 ELECTRICAL CHARACTERISTICS**

It	ltem		Test Condition	Min.	Тур.	Max.	Unit
Logic sup	Logic supply Voltage			4.5	5	5.5	V
LCD Drive		$V_{OP}=V_{DD}-V0$		4.1	4.3	4.5	V
	"H" Level (Except OSC1)	V IH1		0.7 <i>V</i> <sub>DD</sub>	-	$V_{_{DD}}$	V
	"L" Level (Except OSC1)	V IL1	Ta = 25 °C VDD=5V±5%	-0.3	-	0.55	V
Input Voltage	nput Voltage "H" Level V IH2 (OSC1) V IH2 "L" Level V IL2			0.7 <i>V<sub>DD</sub></i>	-	$V_{\scriptscriptstyle DD}$	V
				-0.2	-	0.2 <i>V<sub>DD</sub></i>	V
Frame Frequency		f <sub>FLM</sub>		-	75	-	Hz
Current C	onsumption	I <sub>DD</sub>		-	1.29	-	mA

#### 3-3 BACKLIGHT

#### 3-3-1. Absolute Maximum Ratings

ltem	Symbol	Condition	min	Тур	Max	Unit
Forward Current	IF	Ta = 25 °C	-	-	20	mA
Power Dissipation	PD	Ta = 25 C	-	-	100	mW
Reverse Current	IR	VR=5.0V/LED	-	-	15	uA

#### **3-3-2. Electrical-optical Characteristics**

Item	Symbol	Condition	min		min Typ		Max		Unit				
Forward Current	IF		- Vf=5.0V Ta = 25 °C 75		-		12		15		mA		
Average Luminous Intensity	lv	Vf=5.0V Ta = 25 °C			75		75		-		cd/m <sup>2</sup>		
Colour coordonate	_		Х	Y	Х	Y	Х	Y	_				
			0.25	0.25	0.28	0.28	0.31	0.31					
BackLight Half life Time	-	IF=12mA Ta=25°C	30000		30000		30000		-			-	Hours

The brightness is measured without LCD panel

For operation above 25 °C, The lfm & Pd must be derated , the current derating is -0.36mA/ °C for DC drive and -0.86mA/ °C for Pulse drive ,the Power dissipation is -0.75mW/ °C. The product working current must not more than the 60% of the lfm or lfp according to the working temperature.

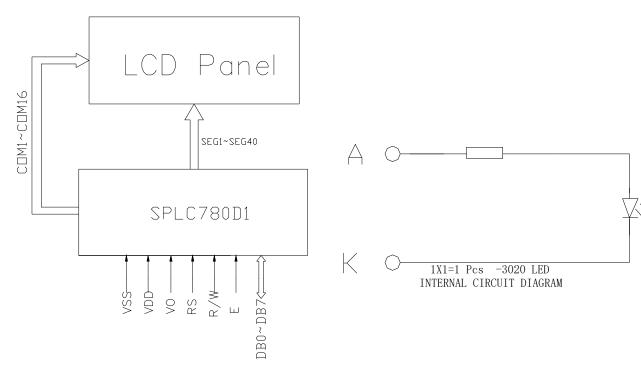
Backlight lifetime means luminance value larger than half of the original after 20000 hours' continuous working.

# 4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

#### **4-1 INTERFACE PIN FUNCTION DESCRIPTION**

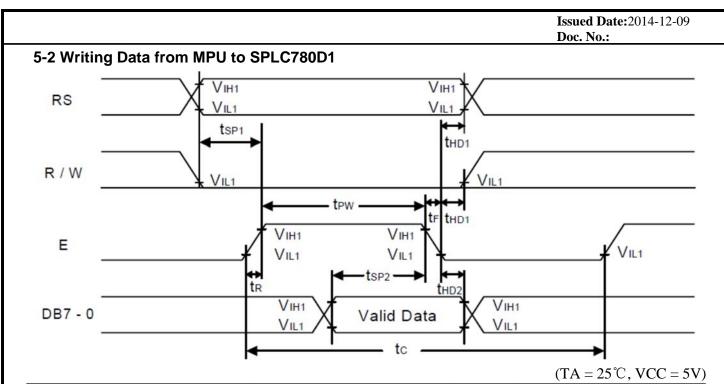
PIN NO.	SYMBOL	FUNCTIONS				
1	VSS	Ground				
2	VDD	Supply voltage for logical circuit				
3	V0	Supply voltage for LCD driving				
4	RS	A signal for selecting registers. I: Data Register (for read and write) ): Instruction Register (for write)				
5	R/W	A signal for selecting read or write actions.1: Read, 0: Write.				
6	Е	A enable signal for reading or writing data.				
7-14	DB0~DB7	8 Bit Data Bus				
15	К	Backlight(-)				
16	Α	Backlight(+5V)				

#### 4-2 BLOCK DIAGRAM



#### **5. TIMING CHARACTERISTICS** 5-1 Reading Data from SPLC780D1 to MPU VIH1 VIH1 RS VIL1 VIL1 t<sub>SP1</sub> tHD1 VIH1 VIH1 R/W tPW tHD1 VIH1 VIH1 Е VIL1 VIL1 VIL1 tD tHD2 VIH1 VIH1 **DB0 - DB7** Valid Data VIL1 VIL1 tc (TA = 25℃, VCC = 5V)

Characteristics	<b>a</b>	Limit				
	Symbol	Min.	Тур.	Max.	Unit	Test Condition
E Cycle Time	t <sub>c</sub>	400	-	-	ns	Pin E
E Pulse Width	tw	150	-	-	ns	Pin E
E Rise/Fall Time	t <sub>R</sub> , t <sub>F</sub>	-	-	25	ns	Pin E
Address Setup Time	t <sub>SP1</sub>	30	-	-	ns	Pins: RS, R/W, E
Address Hold Time	t <sub>HD1</sub>	10	-	-	ns	Pins: RS, R/W, E
Data Output Delay Time	t <sub>D</sub>	-	-	100	ns	Pins: DB0 - DB7
Data hold time	t <sub>HD2</sub>	5.0			ns	Pin DB0 - DB7



Characteristics	0 mb al	Limit			Unit	Test Can dition
Characteristics	Symbol	Min.	Тур.	Max.	Unit	Test Condition
E Cycle Time	tc	400	-	-	ns	Pin E
E Pulse Width	t <sub>PW</sub>	150	-	-	ns	Pin E
E Rise/Fall Time	t <sub>R</sub> , t <sub>F</sub>	-	-	25	ns	Pin E
Address Setup Time	t <sub>SP1</sub>	30	-	-	ns	Pins: RS, R/W, E
Address Hold Time	t <sub>HD1</sub>	10	-	-	ns	Pins: RS, R/W, E
Data Setup Time	t <sub>SP2</sub>	40	·	-	ns	Pins: DB0 - DB7
Data Hold Time	t <sub>HD2</sub>	10	-	-	ns	Pins: DB0 - DB7

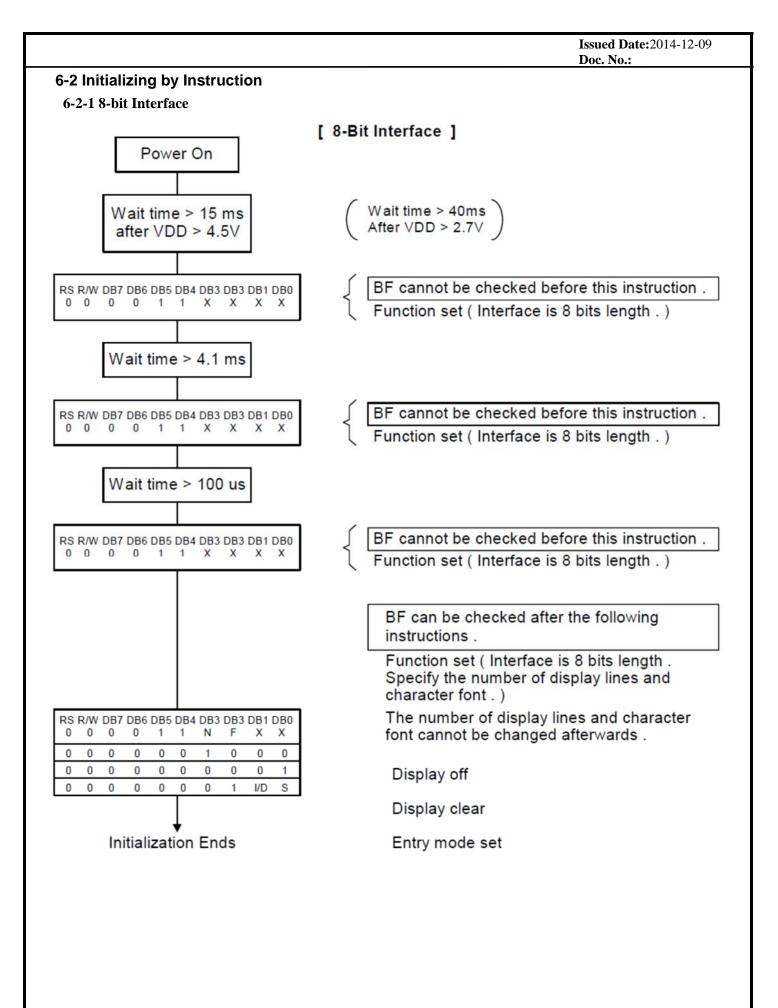
## **6 COMMAND LIST**

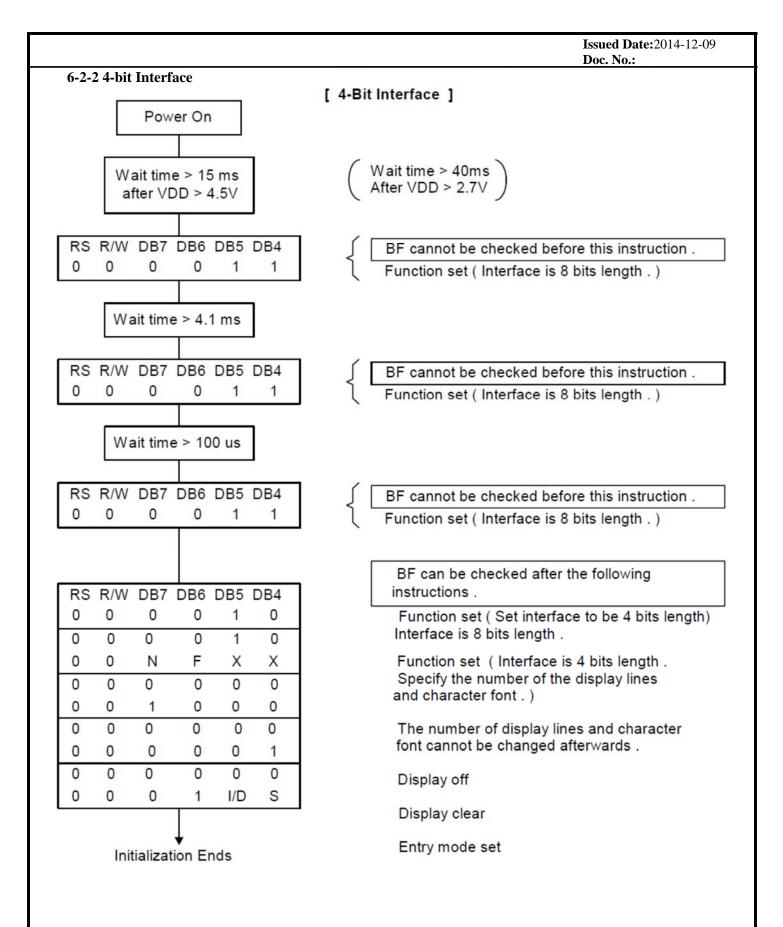
#### 6-1 Instruction Table

Instruction				Ins	structi	on Co	ode				Description		ecution til emp = 25°	
Instruction	RS	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Description	Fosc= 190KHz	Fosc= 270KHz	Fosc= 350KHz
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM and set DDRAM address to "00H" from AC	2.16ms	1.52ms	1.18ms
Return Home	0	0	0	0	0	0	0	0	1		Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	2.16ms	1.52ms	1.18ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	S	Assign cursor moving direction and enable the shift of entire display	53µs	38µs	29µs
Display ON/ OFF Control	0	0	0	0	0	0	1	D	с	в	Set display (D), cursor(C), and blinking of cursor(B) on/off control bit.	53µs	38µs	29µs
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	-	-	Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	53μs	38µs	29µs
Function Set	0	0	0	0	1	DL	N	F	-	-	Set interface data length (DL: 8-bit/4-bit), numbers of display line (N: 2-line/1-line) and, display font type (F:5x10 dots/5x8 dots)	53µs	38µs	29µs
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter.	53µs	38µs	29µs
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter	<mark>53μs</mark>	38µs	29µs
Read Busy Flag and Address Counter	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.			
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM).	53µs	38µs	29µs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM).	53µs	38µs	29µs

Note1: "--": don't care

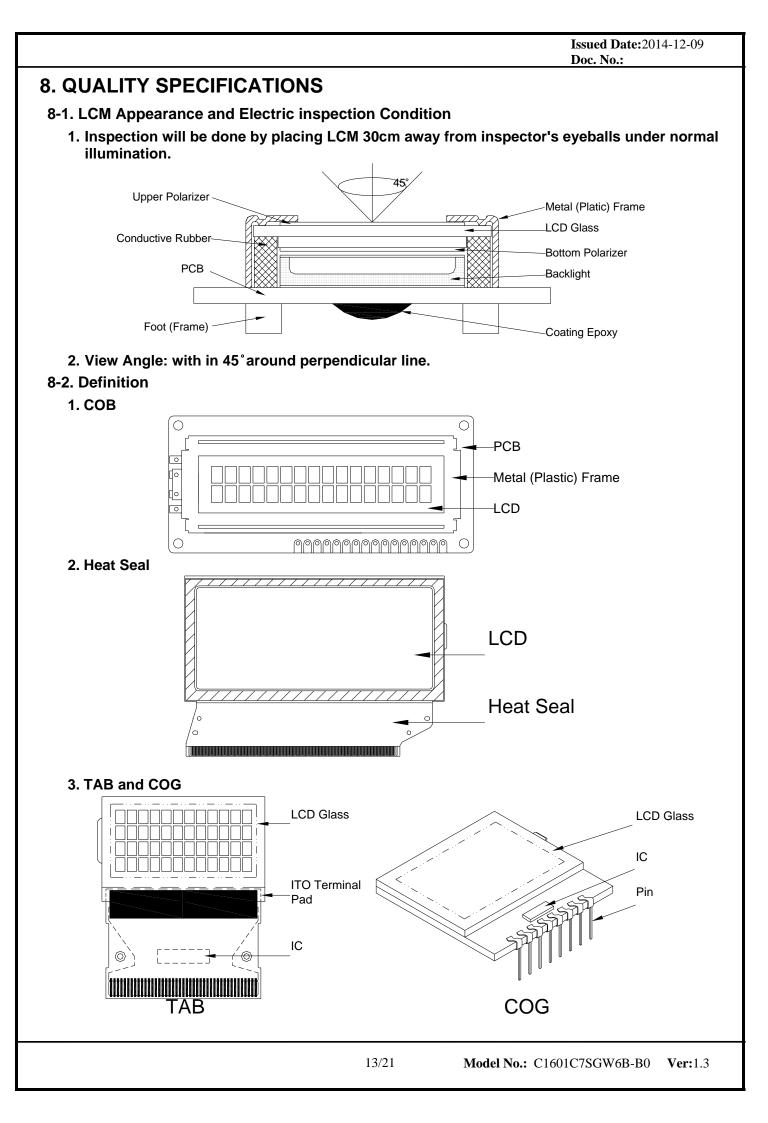
Note2: In the operation condition under -20°C ~ 75°C, the maximum execution time for majority of instruction sets is 100us, except two instructions, "Clear Display" and "Return Home", in which maximum execution time can take up to 4.1ms.





# 7.CHARACTER GENERATOR ROM

Upper 4 bit	LLLL	LLLH	LLHL	LLHH	LHLL	LHLH	LHHL	LHHH	HLLL	HLLH	HLHL	HLHH	HHLL	HHLH	HHHL	нннн
Lower 4 bit																
LLLL																
LLLH																
LLHL																
LLHH																
LHLL																
LHLH																
LHHL																
LHHH																
HLLL																
HLLH																
HLHL																
HLHH																
HHLL																
HHLH																
HHHL																
нннн										H						



#### 8-3. Sampling Plan and Acceptance

#### 1.Sampling Plan

MIL - STD - 105E (  $\parallel$  ) ordinary single inspection is used.

2.Acceptance

Major defect:AQL = 0.65%Minor defect:AQL = 1.5%

#### 8-4. Criteria

#### 1.COB

Inspection Item	Inspection Standards	
PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm <sup>2</sup>	Reject
Height of coating epoxy	Exceed the dimension of drawing	Reject
Void or hole of coating epoxy	Expose bonding wire or IC	Reject
PCB cutting defect	Exceed the dimension of drawing	Reject
	PCB copper flakes peeling off Height of coating epoxy Void or hole of coating epoxy	PCB copper flakes peeling offAny copper flake in viewing Area should be greater than 1.0mm²Height of coating epoxyExceed the dimension of drawingVoid or hole of coating epoxyExpose bonding wire or IC

#### 2. SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing , extra, wrong component or wrong orientation		Reject
Minor	Component position shift x component soldering pad x $y$	X < 3/4Z Y > 1/3D	Reject Reject
Minor	Component tilt component D Soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component PAD PCB	<i>θ</i> ≤ 20°	Reject

				Doc. No.:		
Metal (Plast	ic) Frame					
Defect	Inspection Item	l li	nspection Standa	rds		
Major	Crack / breakage	Any	where	Reject		
		W	L	Acceptable of Scratch		
		w<0.1mm	Any	Ignore		
		0.1 <u>&lt;</u> w<0.2mm	L <u>&lt;</u> 5.0mm	2		
Minor	Frame Scratch	0.2 <u>&lt;</u> w<0.3mm	L <u>&lt;</u> 3.0mm	1		
_		w <u>&gt;</u> 0.3mm	Any	0		
		Note : 1. Above criteria applicable to scratch lin with distance greater than 5mm. 2. Scratch on the back side of frame (not visib can be ignored .				
				Acceptable of Dents / Pricks		
		Ф <u>&lt;</u>	2			
	Frame Dent , Prick	1.0<4	1			
Minor	$\Phi = \frac{L + W}{2}$	1.5r	0			
	2	Note : 1. Above criteria applicable to any two der / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (r visible) can be ignored				
Minor	Frame Deformation	Excee	d the dimension of	drawing		
Minor	Metal Frame Oxidation		Any rust			

#### 4. Flexible Film Connector (FFC)

Defect	Insp	ection Item	Inspection Standa	rds	
Minor	Tilted soldering		Tilted soldering Within the angle +5°		Acceptable
Minor	Uneven s	older joint /bump		Reject	
			Expose the conductive line	Reject	
Minor	Hole	$\Phi = \frac{L + W}{2}$	$\Phi$ > 1.0mm	Reject	
Minor	Position shift $Y \xrightarrow{\psi} \xrightarrow{Z_{\leftarrow}} \psi$		Y > 1/3D	Reject	
Minor			X > 1/2Z	Reject	

#### 5. Screw

Defect Inspection Item Inspection Standards					
Major	Screw missing/loosen		Reject		
Minor	Screw oxidation	Any rust	Reject		
Minor	Screw deformation	Difficult to accept screw driver	Reject		

#### 6. Heatseal TCP FPC

Defect	Inspection Item	Inspection Standards		
Major	Scratch expose conductive layer		Reject	
Minor	HS Hole $\Phi = \frac{L + W}{2}$	$\Phi$ > 0.5mm	Reject	
Major	Adhesion strength	Less than the specification	Reject	
Minor	Position shift $Y \xrightarrow{-\frac{1}{2}} \xrightarrow{-\frac{1}{2}$	Y > 1/3D	Reject	
WIITIO		X > 1/2Z	Reject	
Major	Conductive line break		Reject	

#### 7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards					
		Acceptable number of units					
		⊕ <u>&lt;</u> 0.10mm	Ignore				
		0.10<⊕ <u>&lt;</u> 0.15mm	2				
Minor	LED dirty, prick	0.15<⊕ <u>&lt;</u> 0.2mm	1				
		⊕>0.2mm	0				
		The distance between any two spots should be <u>&gt;</u> 5mm Any spot/dot/void outside of viewing area is acceptable					
Minor	Protective film tilt	Not fully cover LCD	Reject				
Major	COG coating	Not fully cover ITO circuit	Reject				

#### 8. Electric Inspection

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

	-		1				-			
Defect	Insp	ect Item		1		spectior		tandards		
		* Glass Scratch	W			0.03	0.	03 <w<u>&lt;0.0</w<u>	5 V	<u>V&gt;0.05</u>
Minan	Linear Defect	* Polarizer Scratch	L ACC.		Ŀ	<5	_	L<3		Any
Minor	Linear Delect	* Fiber and Linear	NO.			1		1		Reject
		material	Note	L is the length and W is the width of the defec					fect	
		* Foreign materia		Ф <u>&lt;</u>	0.1	0.1<⊕ <u>&lt;</u> 0	).15	0.15<⊕ <u>&lt;</u> 0	.2	<b>⊕&gt;0.2</b>
		between glass and		3E/		2		1		0
Minor	Black Spot and Polarizer Pricked	polarizer or glass and glass * Polarizer hole of protuberance by external force	Note	100mm²     2     1       Φ is the average diameter of the defect.       Distance between two defects > 10mm.						
		* Unobvious	Ŧ		Ф <u>&lt;</u> (	0.3	0.3	<Φ <u>&lt;</u> 0.5	0.	<b>5&lt;</b> ⊕
		transparant foreigr material betweer	1.00.	3E/	A / 1(	00mm <sup>2</sup>		1		0
White Spot Minor and Bubble ir polarizer		glass and glass of glass and polarizer * Air protuberance between polarizer and glass	Note			•		r of the de fects > 10n		
			Φ	⊕ <u>&lt;</u> 0	.10	0.10<⊕ <u>&lt;</u>	<u>&lt;</u> 0.20	0.20<⊕ <u>∢</u>	<u>&lt;</u> 0.25	Φ <b>&gt;0</b> .
	Segment Defect		ACC. NO.	3EA 100m		2		1		0
Minor				W is r	nore	than 1/2 s	segme	ent width		Reje
			Note	$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm			m			
			Φ	Φ <u>&lt;</u> 0.10 0.10<Φ <u>&lt;</u> 0		<u>&lt;</u> 0.20 0.20<⊕ <u>&lt;</u> 0.25		Φ <b>&gt;0</b> .		
	Protuberant	W K K K K K K K K K K K K K K K K K K K	W	Glu	le	W <u>&lt;</u> 1/2 W <u>&lt;</u> 0.		W <u>&lt;</u> 1/2 W <u>&lt;</u> 0		Igno
Minor	Segment	Φ = ( L + W ) / 2	ACC. NO.	3E/ 100m		2		1		0
			1. Seg	ment						
			E			0.4mm		B <u>&lt;</u> 1.0mm		I.0mm
Minor	Assembly Mis-alignment					A<1/2B		-A<0.2		<0.25
	wis-alignment		Judge         Acceptable         Acceptable         Acceptable           2. Dot Matrix         Acceptable         Acceptable         Acceptable         Acceptable							
							Reje			
Minor	Stain on LCD Panel Surface		a simi	lar one	e. Ot		udgeo	d lightly with d according pot"		

## 9. RELIABILITY

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity	50℃, 90%RH, 96Hrs	2	GB/T2423.3 -2006
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test	-20°C, 60min~70°C, 60min, 20 cycles.	2	GB/T2423.2 2 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X,Y,Z 30 min for each direction.	2	GB/T5170.1 4 -2009
8	Electrical Static Discharge	Air: $\pm$ 8KV 150pF/330 $\Omega$ 5 times	2	GB/T17626.
0	Electrical Static Discharge	Contact: $\pm 4$ KV 150pF/330 $\Omega$ 5 times	2	-2006
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	2	GB/T2423.8 -1995

Note: 1) Above conditions are suitable for our company standard products.

2) For restrict products, the test conditions listed as above must be revised.

### 10. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

- (2) Caution of LCD handling & cleaning
  - When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.
  - Isopropyl alcohol
  - Ethyl alcohol
  - Trichloro trifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water
- Ketone

- Aromatics

(3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

- (4) Packaging
  - Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
  - To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.
- (5) Caution for operation
  - It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
  - Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
  - If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
  - A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
  - Usage under the relative condition of 40°C, 50%RH or less is required.

#### (6) Storage

- In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.
  - Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
  - It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol. Which should be burned up later.
  - When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.
- (8) Other
  - After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

